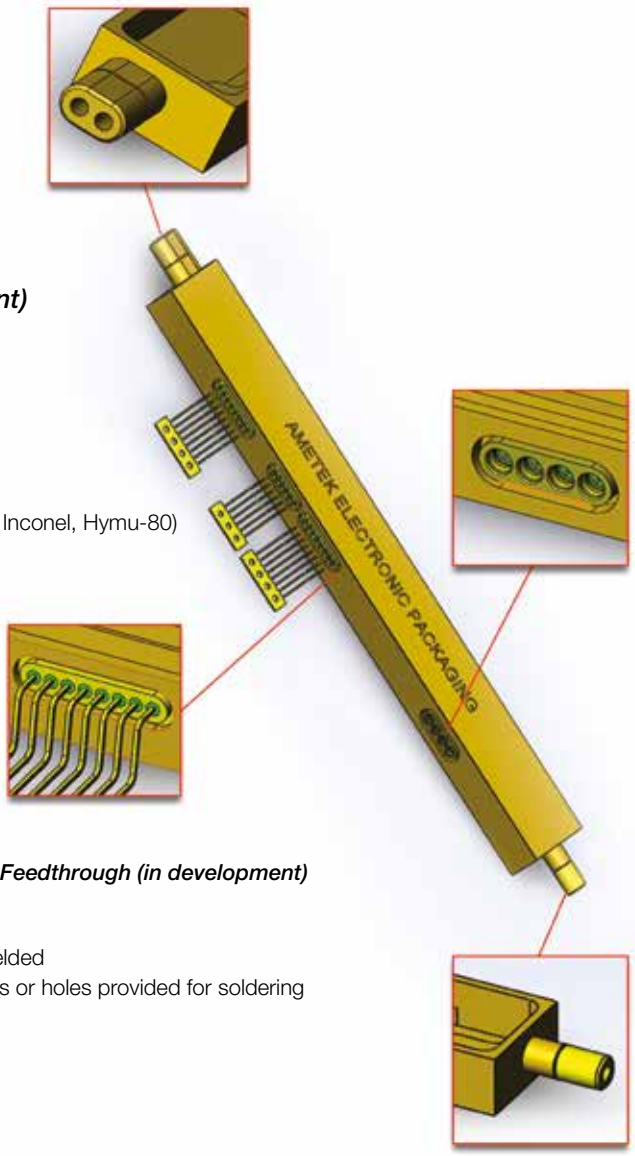
Optical Modulator Housing

AMETEK ECP's modulator housing design offers versatility and reliability for today's high-performance optical equipment. The housing is designed to enable optical devices used for 100G and 400G applications for long-haul, metro and data center interfaces.

A Small Form Factor (SFF) housing footprint compliant to the ***OIF 100G Implementation Agreement*** is also available.



KEY FEATURES

- Hermetic housing
- Rugged design
- Various RF connectivity options including the newly-patented ***S-BEND Ceramic Feedthrough*** *(in development)*
- Bandwidth performance to 400G
- Various body material and plating options
- Performance that meets or exceeds industry standards

Housing:

Material: Stainless steel, cold-rolled steel, Kovar, high-Nickel alloys (Monel, Inconel, Hymu-80)
Construction: Single piece machined, multi-piece machined

DC Connectors:

Construction: Direct seal, brazed terminals, welded connector
Insulator: Glass, alumina
Leads: Flat or round, straight or gull-winged

RF Connectors:

Construction: Direct seal, brazed terminals, welded connector
Insulator: Glass, alumina
Inside Termination: Rounded end, straight cut, turned down, flattened
Outside Termination: SMA series, SMPx series, FPC, ***S-BEND Ceramic Feedthrough (in development)***

Input/Output Ports:

Construction: Integrally machined in the housing, multi-piece brazed or welded
Design: Straight, angled, single or dual, round or square or rectangular, slots or holes provided for soldering
Plating: General, selective

Plating:

Metals: Ni (electrolytic or electroless), Au (electrolytic or electroless), Ag, Pd
Type: General, selective

Workmanship and Performance Standards:

• JEDEC Standard 9 • Mil-Std-883 • Mil-Std-202 • Telcordia

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